# OP \$40.00 11720

# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

## **CONVEYING PARTY DATA**

Name	Execution Date
Kuniaki TAKAHASHI	07/24/2007
Toshiya HAMADA	07/26/2007
Yasushi FUJINAMI	07/27/2007

## **RECEIVING PARTY DATA**

Name:	SONY CORPORATION	
Street Address:	1-7-1 Konan, Minato-ku	
City:	Tokyo	
State/Country:	Japan	
Postal Code:	108-0075	

Name:	SONY COMPUTER ENTERTAINMENT INC.	
Street Address:	2-6-21, Minami-Aoyama, Minato-ku	
City:	Tokyo	
State/Country:	JAPAN	
Postal Code:	107-0062	

### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11720806

## **CORRESPONDENCE DATA**

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PATENT

500446020 REEL: 020402 FRAME: 0929

ATTORNEY DOCKET NUMBER:	307690US8X PCT	
NAME OF SUBMITTER:	Etsegenet Nega	
Total Attachments: 2 source=307690USAssignment#page1.tif source=307690USAssignment#page2.tif		

PATENT REEL: 020402 FRAME: 0930

Docket Number: Docket No.

307690US8X PCT

### ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name are listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

ENCODING APPARATUS AND METHOD, DECODING APPARATUS AND METHOD, PROGRAM, RECORD MEDIUM, AND DATA STRUCTURE

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, 108-0075 Japan and SONY COMPUTER ENTERTAINMENT INC. with offices at 2-6-21, Minami-Aoyama, Minato-ku, Tokyo 107-0062, Japan (hereinafter referenced as ASSIGNEES) are desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, their successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignees of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or their designee, as ASSIGNEES or their successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at their own expense;

And I further agree that ASSIGNEES will, upon their request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 11/720,806 Filing Date: June 4, 2007

This assignment executed on the dates indicated below.

PATENT REEL: 020402 FRAME: 0931

Kuniaki TAKAHASHI	
Name of first or sole inventor	Execution date of U.S. Patent Application
Tokyo, Japan Residence of first or sole inventor	
Residence of first or sole inventor	
Signature of first or sole inventor	July 24, 2007  Date of this assignment
Signature of first gr sole inventor	Date of this assignment
Toshiya HAMADA Name of second inventor	Execution date of U.S. Patent Application
	Execution date of old, I atom Hippinearion
Saitama, Japan Residence of second inventor	
	-
Signature of second inventor	Date of this assignment
Signature of second inventor	Date of this assignment
Yasushi FUJINAMI Name of third inventor	Execution date of U.S. Patent Application
	Execution date of 0.0. Fatonic Approach
Tokyo, Japan Residence of third inventor	
	7/20-10
Signature of third inventor	July 27. 2007  Date of this assignment
Signature of third inventor	Date of this assignment
Name of fourth inventor	Execution date of U.S. Patent Application
Residence of fourth inventor	
Signature of fourth inventor	Date of this assignment
Name of fifth inventor	Execution date of U.S. Patent Application
Residence of fifth inventor	
Signature of fifth inventor	Date of this assignment

**RECORDED: 01/23/2008** 

**PATENT REEL: 020402 FRAME: 0932**